501910294 05/04/2012

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
Martin Lee Riker	05/15/2009
Keith A. Miller	05/15/2009
Anantha Subramani	05/15/2009

RECEIVING PARTY DATA

Name:	Applied Materials, Inc.	
Street Address:	3050 Bowers Avenue	
City:	Santa Clara	
State/Country:	CALIFORNIA	
Postal Code:	95054	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	13457441	

CORRESPONDENCE DATA

Fax Number: (732)530-9808 Phone: 732-530-9404

Email: adevesty@pattersonsheridan.com, psdocketing@pattersonsheridan.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US

Mail.

Correspondent Name: Patterson & Sheridan, LLP
Address Line 1: 595 Shrewsbury Avenue

Address Line 2: Suite 100

Address Line 4: Shrewsbury, NEW JERSEY 07702

ATTORNEY DOCKET NUMBER: APPM/13428 D1 KT/AMD

NAME OF SUBMITTER: Keith Taboada

Total Attachments: 2

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PATENT REEL: 028155 FRAME: 0765 OF \$40.00 1345/441

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Atty Dkt No.: 013428/AGS/SPARES/DP

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Martin Lee Riker 2174 Lacey Drive Milpitas, California 95036 5 MLC	2)	Keith A. Miller 535 San Pierre Way Mountain View, California 94043
3)	Anantha Subramani 4245 Meriot Court San Jose, California 95135		
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(hereinafter referred to as Assignors), have invented a certain invention entitled:

WAFER PROCESSING DEPOSITION SHIELDING COMPONENTS

for which application for Letters Patent in the United States was filed on April 14, 2009, under Serial No. 12/423,444, executed on even date herewith; and

WHEREAS, APPLIED MATERIALS, INC., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

- 1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.
- 2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition

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proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

- 3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.
- 4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) 5/15/09 (DATE)

2) <u>5/15/59</u> (DATE)

3) 5/19/09 (DATE)

Martin, Lee Riker

Kejth A. Miller

Anantha Subramani